



ThinFlex

ThinFlex Corporation

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ThinFlex H-0503ES

Adhesiveless Copper Clad Laminate

(Halogen Free)

ThinFlex H-0503ES is an adhesiveless metal clad polyimide film, furnished in the form of roll laminate with ED copper on one side. ThinFlex H-0503ES adhesiveless composites are designed for a wide variety of flexible circuit applications which require advanced material performance, temperature resistance, fine pitch, and high reliability.

1. Product Characteristics:

- * Excellent dimensional stability
- * Excellent flexibility
- * Finer line etching capability
- * Low moisture absorption
- * Excellent flammability (Flame class UL 94V-0; UL File No. E219724)
- * Excellent chemical resistance
- * Excellent thermal, mechanical, and electrical properties

2. Specifications:

H - 05 03 E S				
Product H : 2-FCCL	Thickness of PI 05 : 0.5 mil	Thickness of Cu 03 : 1/3 oz	Cu Type E : ED	Structure Single-sided
Supply Size	W: 250/500 \pm 1mm; L: 100 +2/-0m (roll type), splice \leq 3			

***Other thicknesses and dimensions are available on customers' demand.**



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3. Construction:

Copper foil

4. Properties:

Polyimide film

Test item	Unit	H-0503ES	Test Method
Peel Strength			
As Received	Kgf/cm	≥ 0.7	IPC-TM650 2.4.9 B
Solder Float	Kgf/cm	≥ 0.7	IPC-TM650 2.4.13 B
After Temp. Cycling	Kgf/cm	≥ 0.7	IPC-TM650 2.4.9
Chemical Resistance	Kgf/cm	≥ 0.7	IPC-TM650 2.3.2
Tensile Strength (Base Film)	Kg/mm ²	23	IPC-TM-650 2.4.19
Elongation (Base Film)	%	22	IPC-TM-650 2.4.19
Tensile Modulus (Base Film)	Kg/mm ²	700	ASTM D882
Initial Tear Strength (Base Film)	g	420	IPC-TM-650 2.4.16
Propagation Tear Strength (Base Film)	g	10	IPC-TM-650 2.4.17.1
Flexural Endurance, MIT			
M.D.	Cycles	≥ 1200	JIS-C 6471, 0.8mmR, 0.5kg
T.D.	Cycles	≥ 1200	JIS-C 6471, 0.8mmR, 0.5kg
Electrical Properties			
Surface Resistance	Ω	~10 ¹¹	IPC-TM650 2.5.17
Volume Resistance	Ω-cm	~10 ¹²	IPC-TM650 2.5.17
Insulation Resistance	Ω	~10 ⁹	IPC-TM650 2.6.3.2
Dielectric Strength	kV/mil	5.0	ASTM-D149
Dielectric Constant	-	3.6	IPC-TM650 2.5.5.3
Dissipation factor	-	0.01	IPC-TM650 2.5.5.3
Physical and Thermal Properties			
Dimensional Stability M.D.	%	-0.1~0.1	IPC-TM650 2.2.4C
Dimensional Stability T.D.	%	-0.1~0.1	IPC-TM650 2.2.4C
CTE	ppm/°C	26	ThinFlex
T _g	°C	327	ThinFlex
Solder Float 10sec at 288°C (550°F)	-	Pass	IPC-TM650 2.4.13
Moisture Absorption Test	%	1.1	IPC-TM650 2.6.2
Chemical Resistance-single	-	Pass	IPC-TM650 2.3.2
Thickness tolerance	um	25±10%	ThinFlex
UL Flame Class	-	94V-0	UL

* Above data are typical values, and are not guaranteed values.

Technical Data Sheet: 201201



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5. Storage:

ThinFlex H-0503ES will meet its shelf-life for at least 12 months after arrival at the user's factory when stored in the original packaging at temperatures of below 25°C and below 70% humidity. The products do not need refrigeration and should not be frozen.

Note: The information and data contained in this technical literature is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.

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